

E1

DATE 23 OCT 2015

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- Y 14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF b DIMENSION AT MAXIMUM MATERIAL CONDITION.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSIONS.

 5. MAXIMUM MOLD PROTRUSION OR FLASH TO
- BE 0.15 PER SIDE.

	MILLIMETERS	
DIM	MIN	MAX
Α	2.35	2.65
A1	0.00	0.10
b	0.35	0.49
С	0.25	0.32
D	10.15	10.45
D1	1.79	2.00
E	7.40	7.60
E1	2.27	2.47
е	1.27 BSC	
Н	10.05	10.55
h	0.53 REF	
L	0.50	0.90
M	0°	7°

GENERIC MARKING DIAGRAM*



= Specific Device Code XXX = Assembly Location Α

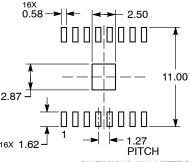
WL = Wafer Lot = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED **SOLDERING FOOTPRINT**

▋▋▋▋¦▋▋▋▋

BOTTOM VIEW



DIMENSIONS: MILLIMETERS

Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON96277F Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** SOIC-16 WB, EP **PAGE 1 OF 1**

ON Semiconductor and (III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.